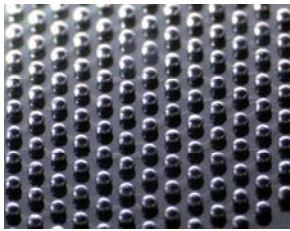




DEK's Packaging Innovations Land Two Industry Honors



DEK continues to receive praise for its forward-looking technology advancements and ongoing commitment to pioneering process solutions. At last week's Semicon West event in San Francisco, California, the company was the recipient of two acclaimed industry awards in recognition of DEK's efforts to further manufacturing technology and productivity.

For its ground-breaking Galaxy DirEKt Ball Placement™ system, DEK was honored with an Editors' Choice Award from *Semiconductor International* magazine. Selected as a product that has significantly contributed to technology excellence, the Galaxy DirEKt Ball Placement system completely redefines packaging productivity. The technology offers semiconductor specialists the ability to deposit solder spheres at substrate- and wafer-level, allowing placement of solder balls as small as 0.2mm in diameter at 03mm pitch and delivering first pass yields of over 99%. Unlike other methods that employ serial approaches to ball placement, the parallel processing capabilities of the Galaxy DirEKt Ball Placement system allows for amazingly repeatable accuracy and incredibly fast cycle times that are completely independent of I/O count. Plus, because of its built-in flexibility, the platform can be easily redeployed to host a variety of other processes including, but not limited to, encapsulation, wafer bumping, backside wafer coating and thermal interface materials deposition.

In addition to the capabilities of the next-generation systems that host various packaging processes, the ability to successfully produce advanced devices is also highly dependent upon the tooling and support mechanisms used to provide in-process stability. To address

the issues commonly associated with older generation carrier systems, DEK has engineered Virtual Panel Carrier (VPC) -- a unique substrate centering and transport technology that delivers extraordinary parts stability and unmatched ease of use. Through an innovative centering technology, VPC eliminates the possibility of even slight misregistration while providing simple, multi-process functionality. Unlike other systems that require individual component fiducials, VPC references parts using two global fiducials, thus enabling the easy transfer of VPC throughout all assembly processes and dramatically improving throughput while also reducing costs. The ingenuity of this latest DEK innovation has now also earned the distinction of being award-winning, as VPC was honored with an Advanced Packaging Award at a special ceremony during last week's Semicon West event.

“Technical advancement and engineering expertise are cornerstones of DEK’s ‘Expect More’ philosophy and key components of our long-term success,” comments DEK CEO, John Hartner. “It is very gratifying to know that the industry has also recognized our efforts and selected DEK’s Galaxy DirEKt Ball Placement and VPC systems for two such prestigious awards.”

For more information on Galaxy DirEKt Ball Placement and VPC or any of DEK’s market-leading technologies, log onto www.dek.com or call 408-954-8582.

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About DEK

DEK is a global provider of advanced pre-placement manufacturing solutions and innovative deposition technologies for a wide range of electronic materials. For more information, visit DEK at www.dek.com.

Company Contact	Press Contact
Karen Moore-Watts DEK	Laura Sims for DEK
Tel. +44 1305 760760 Email: kmoore-watts@dek.com Internet: www.dek.com	Tel: 404-661-0348 E-Mail: laura@simscomm.com